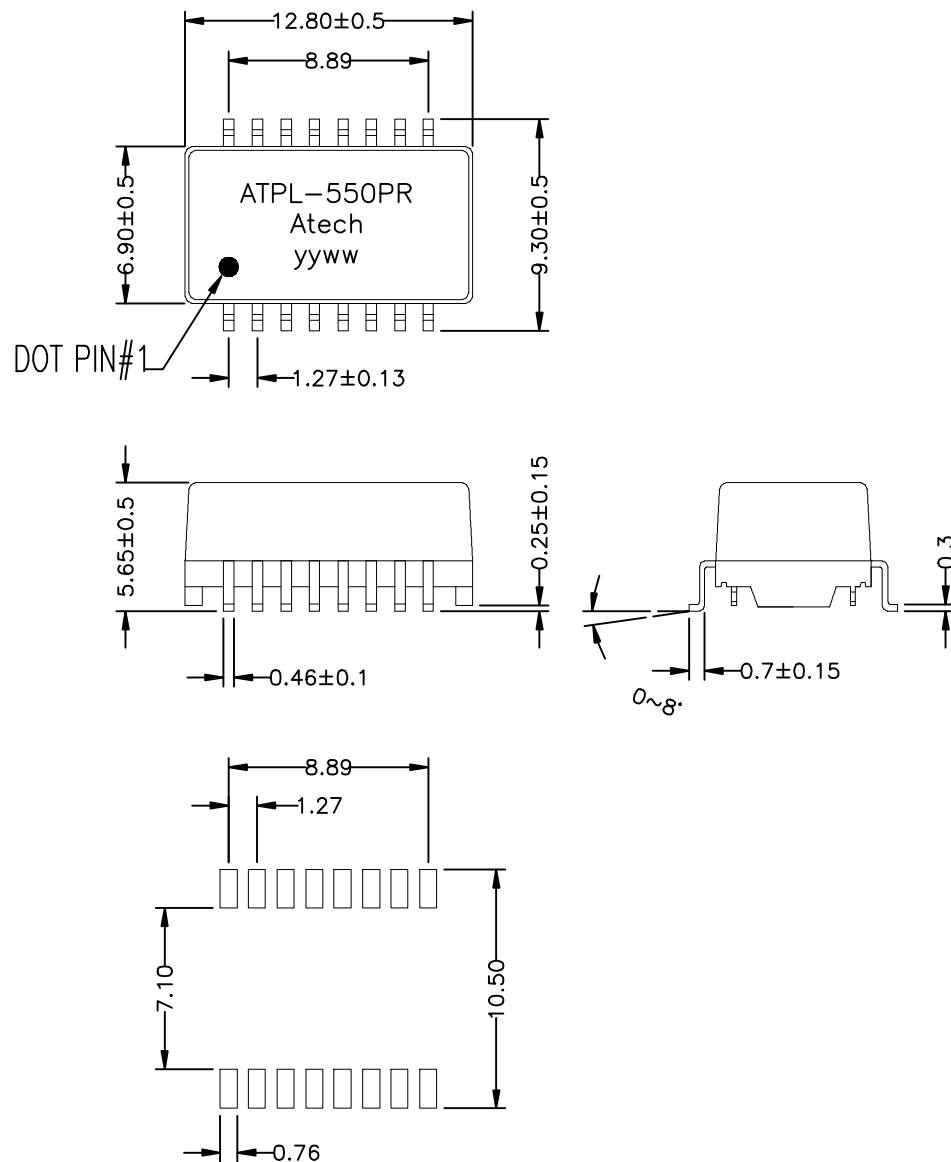
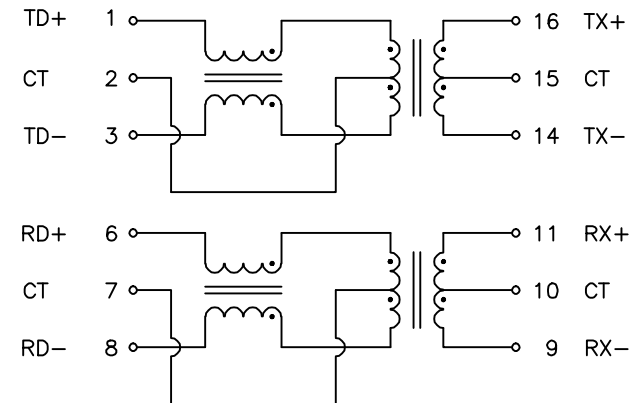




SUGGESTED PAD LAYOUT

TOLERANCES: xx.x0±0.25
0.xx±0.05

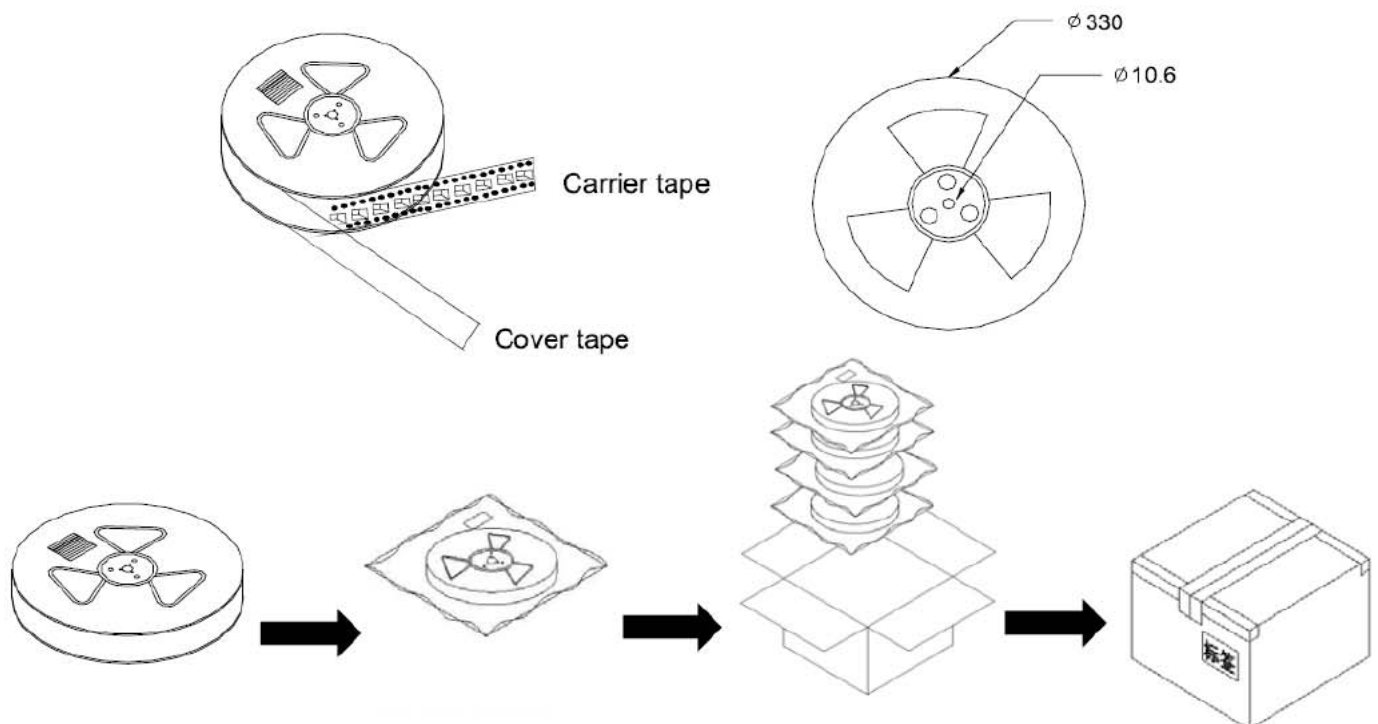
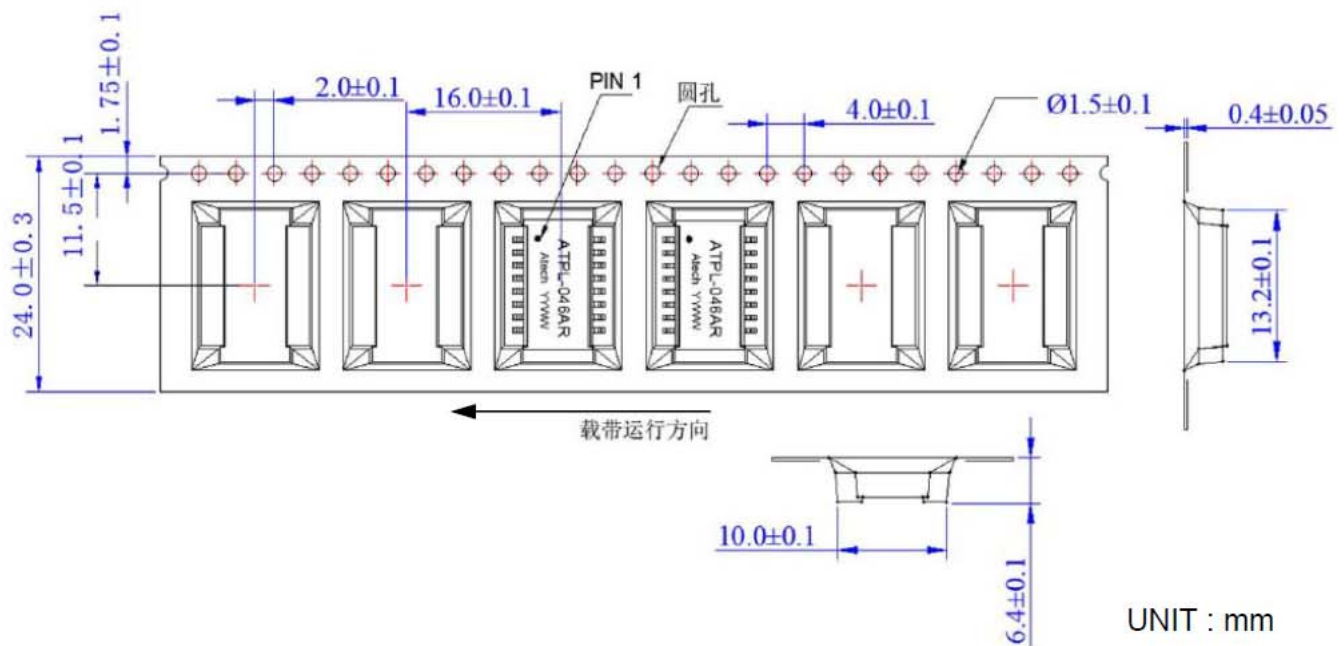


ELECTRICAL SPECIFICATIONS @ 25°C :

1. TURNS RATIO ($\pm 5\%$) : PIN 1-3 : 16-14 = 1CT : 1CT
PIN 6-8 : 11-9 = 1CT : 1CT
2. OCL (@100KHz/0.1V WITH 8mA BIAS) : PIN (1-3/6-8) = 350uH MIN.
3. L.L : 0.5uH MAX.
4. DCR : 1.4Ω MAX.
5. INSERTION LOSS : 1-100MHz = -1.1dB MAX.
6. RETURN LOSS : 1-30MHz = -18dB MIN.
40MHz = -14.4dB MIN.
50MHz = -13.1dB MIN.
60-80MHz = -12dB MIN.
7. CROSS TALK : 1-100MHz = -30dB MIN.
8. DIFFERENTIAL TO COMMON MODE REJECTION : 1-100MHz : -30dB MIN.
9. HI-POT : 1500Vrms, 1mA, 60SEC
10. OPERATING TEMPERATURE RANGE : 0°C~+70°C
11. STORAGE TEMPERATURE RANGE : -40°C~+85°C
12. IEEE802.3af compliant performance---350mA Current Capability
13. RoHS COMPLIANT

								TITLE 10/100 BASE-TX PoE TRANSFORMER	
								DWG. NO. ATPL-550PR	
	RELEASE	01/28/2021	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 01/28/21	P/N:	DRAW SHIRLEY	
REVISIONS									

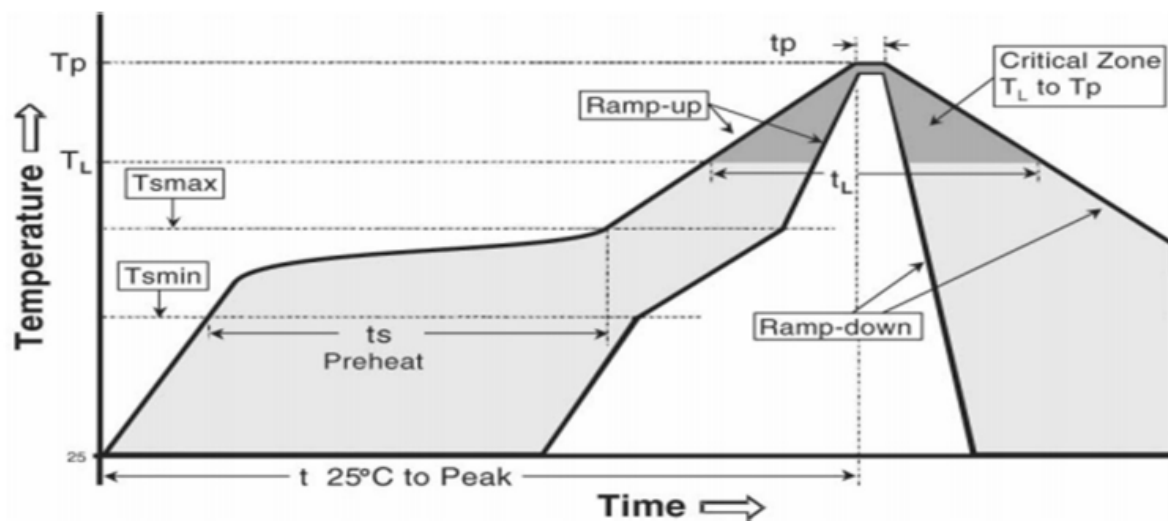
2. Package :



Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 16 PIN Series	600	600x9=5400		0.8

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_{smax} to T_p)	3°C/second max	3°C/second max
Preheat Temperature Min (T_{smin}) Temperature Min (T_{smax}) Time (T_{smin} to T_{smax}) (t_s)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T_L) Time (t_L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T_p)	225°C	260°C
Time within 5°C of actual Peak Temperature (T_p) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max